

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Xu, et al.

Serial No.: 09/352,008

Confirmation No.: 1579

Filed: July 12, 1999

For: New Methodologies To
Reduce Process Sensitivity
To The Chamber Condition

Group Art Unit: 1763

Examiner: Goudreau, G.

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GROUP 1700

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Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

CERTIFICATE OF MAILING
37 CFR 1.8

I hereby certify that this correspondence is being deposited on
November 29, 2001 with the United States Postal Service as First
Class Mail in an envelope addressed to: Assistant Commissioner for
Patents, Washington, D.C. 20231.

11/29/01
Date

Keith M. Decker
Signature

RESPONSE TO OFFICE ACTION DATED SEPTEMBER 29, 2001.

In response to the Office Action dated August 29, 2001, having a shortened statutory period for response set to expire on November 29, 2001, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below. The Commissioner is authorized to charge \$120.00 to Deposit Account No. 20-0782/AMAT/3417/US/ETCH/SILICON/BTP and any other fees necessary to make this response timely.

IN THE CLAIMS:

Please cancel claims 27-29 without prejudice.

Please amend the following claims:

1. (Amended) A method of etching substrates in a chamber having internal surfaces, comprising:

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